

SPECIFICATIONS

4,00



PIN1 2.85 PART ND. 20 DATE CODE 0.45 54X5=12.70 4.90 2

22.50

7.5X<u>2=15.00</u>





Notes:

1. All Dimensions are in millimeters (inches).

2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.

3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Color of Emission Lens Type	
CDTA36R2WF	InGaAIP	Red	White Segment	Common Anode

4.25





TYPICAL INTERNAL EQUIVALENT CIRCUIT









ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	70	mW			
Pulse Forward Current	lfp	90	mA			
Continuous Forward Current	lF	25	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Doromotor	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 20mA	-	20	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	2.0	2.6	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	650	-	nm
Dominant Wavelength	λD	l⊧ = 20mA	-	639	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm





OPTICAL CHARACTERISTIC CURVES





FORWARD VOLTAGE (V) Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE



AMBIENT TEMPERATURE(*C) Fig.3 FORWARD VOLTAGE VS. TEMPERATURE





FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT



AMBIENT TEMPERATURE(°C) Fig.4 RELATIVE INTENSITY VS. TEMPERATURE







SOLDERING CONDITIONS – DISPLAY TYPE LED

• RECOMMEND SOLDERING PROFILE



Note:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- No more than one wave soldering pass

• SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should

be shorter (+10°C \rightarrow 1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within $\leq 3 \text{ sec under } 350^{\circ}\text{C}$. The head of soldering iron cannot touch copper foil.

